



SLOVENSKI STANDARD
oSIST prEN IEC 62680-1-2:2022
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Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2. del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-2: Gemeinsame Komponenten - Festlegung für die USB-Stromversorgung

Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie 1-2: Composants communs - Spécification de l'alimentation électrique par port USB

Ta slovenski standard je istoveten z: prEN IEC 62680-1-2:2022

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ICS:

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER**Part 1-2: Common components – USB Power Delivery specification**

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Robert de Nie	NXP Semiconductors	Philip Leung	Renesas Electronics Corp.
Rod Whitby	NXP Semiconductors	Steve Roux	Renesas Electronics Corp.
Vijendra Kuroodi	NXP Semiconductors	Tetsu Sato	Renesas Electronics Corp.
Winston Langeslag	NXP Semiconductors	Toshifumi Yamaoka	Renesas Electronics Corp.
Robert Heaton	Obsidian Technology	Chunan Kuo	Richtek Technology Corporation
Andrew Yoo	ON Semiconductor	Heinz Wei	Richtek Technology Corporation
Brady Maasen	ON Semiconductor	TZUHSIEN CHUANG	Richtek Technology Corporation
Bryan McCoy	ON Semiconductor	Tatsuya Irisawa	Ricoh Company Ltd.
Christian Klein	ON Semiconductor	Akihiro Ono	Rohm Co. Ltd.
Cor Voorwinden	ON Semiconductor	Chris Lin	Rohm Co. Ltd.
Edward Berrios	ON Semiconductor	Hidenori Nishimoto	Rohm Co. Ltd.
Michael Smith	ON Semiconductor	Kris Bahar	Rohm Co. Ltd.
Oscar Freitas	ON Semiconductor	Manabu Miyata	Rohm Co. Ltd.
Tom Duffy	ON Semiconductor	Ruben Balbuena	Rohm Co. Ltd.
Brian Collins	Parade Technologies Inc.	Takashi Sato	Rohm Co. Ltd.
Craig Wiley	Parade Technologies Inc.	Vijendra Kuroodi	Rohm Co. Ltd.
Aditya Kulkarni	Power Integrations	Yusuke Kondo	Rohm Co. Ltd.
Akshay Nayaknur	Power Integrations	Kazuomi Nagai	ROHM Co., Ltd.
Amruta Patra	Power Integrations	Matti Kulmala	Salcomp Plc
Rahul Joshi	Power Integrations	Toni Lehimo	Salcomp Plc
Ricardo Pregiteer	Power Integrations	Tong Kim	Samsung Electronics Co. Ltd.
Shruti Anand	Power Integrations	Alvin Cox	Seagate Technology LLC
Amit gupta	Qualcomm, Inc	Emmanuel Lemay	Seagate Technology LLC

John Hein	Seagate Technology LLC	Joel Huloux	STMicroelectronics
Marc Noblitt	Seagate Technology LLC	John Bloomfield	STMicroelectronics
Michael Morgan	Seagate Technology LLC	Massimo Panzica	STMicroelectronics
Ronald Rueckert	Seagate Technology LLC	Meriem Mersel	STMicroelectronics
Tony Priborsky	Seagate Technology LLC	Nathalie Ballot	STMicroelectronics
Chin Chang	Semtech Corporation	Pascal Legrand	STMicroelectronics
Tom Farkas	Semtech Corporation	Patrizia Milazzo	STMicroelectronics
Ning Dai	Silergy Corp.	Richard O'Connor	STMicroelectronics
Wanfeng Zhang	Silergy Corp.	Morten Christiansen	Synopsys, Inc.
Kafai Leung	Silicon Laboratories, Inc.	Nivin George	Synopsys, Inc.
Kok Hong Soh	Silicon Laboratories, Inc.	Zongyao Wen	Synopsys, Inc.
Sorin Badiu	Silicon Laboratories, Inc.	Joan Marrinan	Tektronix
Steven Ghang	Silicon Laboratories, Inc.	Kimberley McKay	Teledyne-LeCroy
Abhishek Sardeshpande	SiliConch Systems Private Limited	Matthew Dunn	Teledyne-LeCroy
Aniket Mathad	SiliConch Systems Private Limited	Tony Minchell	Teledyne-LeCroy
Chandana N	SiliConch Systems Private Limited	Anand Dabak	Texas Instruments
Jaswanth Ammineni	SiliConch Systems Private Limited	Bill Waters	Texas Instruments
Jinisha Patel	SiliConch Systems Private Limited	Bing Lu	Texas Instruments
Kaustubh Kumar	SiliConch Systems Private Limited	Deric Waters	Texas Instruments
Nitish	SiliConch Systems Private Limited	Grant Ley	Texas Instruments
Pavitra	SiliConch Systems Private Limited	Gregory Watkins	Texas Instruments
Balasubramanian		Ingolf Frank	Texas Instruments
Rakesh Polasa	SiliConch Systems Private Limited	Ivo Huber	Texas Instruments
Satish Anand Verkila	SiliConch Systems Private Limited	Javed Ahmad	Texas Instruments
Shubham Paliwal	SiliConch Systems Private Limited	Jean Picard	Texas Instruments
Vishnu Pusuluri	SiliConch Systems Private Limited	John Perry	Texas Instruments
John Sisto	SMSC	Martin Patoka	Texas Instruments
Ken Gay	SMSC	Mike Campbell	Texas Instruments
Mark Bohm	SMSC	Scott Jackson	Texas Instruments
Richard Wahler	SMSC	Shafiuddin	Texas Instruments
Shannon Cash	SMSC	Mohammed Srinath Hosur	Texas Instruments
Tim Knowlton	SMSC	Steven Tom	Texas Instruments
William Chiechi	SMSC	Yoon Lee	Texas Instruments
Shigenori Tagami	Sony Corporation	Tim Wilhelm	The Silanna Group Pty. Ltd.
Shinichi Hirata	Sony Corporation	Tod Wolf	The Silanna Group Pty. Ltd.
Amanda Hosler	Specwerkz	Chris Yokum	Total Phase
Bob Dunstan	Specwerkz	Eric Wall	UL LLC
Diane Lenox	Specwerkz	Jason Smith	UL LLC
Michael Munn	StarTech.com Ltd.	Steven Chen	Unigraf OY
Fabien Friess	ST-Ericsson	Topi Lampiranta	Unigraf OY
Giuseppe Platania	ST-Ericsson	Brad Cox	Ventev Mobile
Jean-Francois Gatto	ST-Ericsson	Colin Vose	Ventev Mobile
Milan Stamenkovic	ST-Ericsson	Dydron Lin	VIA Technologies, Inc.
Nicolas Florenchie	ST-Ericsson	Fong-Jim Wang	VIA Technologies, Inc.
Patrizia Milazzo	ST-Ericsson	Jay Tseng	VIA Technologies, Inc.
Christophe Cochard	STMicroelectronics	Rex Chang	VIA Technologies, Inc.
Christophe Lorin	STMicroelectronics	Terrance Shih	VIA Technologies, Inc.
Filippo Bonaccorso	STMicroelectronics	Ho Wen Tsai	Weltrend Semiconductor
Jessy Guilbot	STMicroelectronics	Hung Chiang	Weltrend Semiconductor
		Jeng Cheng Liu	Weltrend Semiconductor